

IN THE CLAIMS:

Please amend the claims as follows:

1. (Currently Amended) A method for patterning a device layer using a patterned stamp, comprising the steps of:

(a) providing a substrate;

(b) bringing the patterned stamp into contact with the substrate;

(c) removing the patterned stamp from the substrate;

~~characterised in that step (2) is carried out so that the surface energy of the substrate is modified in accordance with the pattern; and that the method further comprises a step; and~~

(d) depositing a solution of a device layer on the substrate after the patterned stamp has been removed; whereby the surface energy of the substrate determines the deposition pattern of the device layer

wherein step (b) is carried out so that the surface energy of the substrate is modified in accordance with the pattern.

2. (Canceled)

3. (Canceled)

4. (Currently Amended) A method according to ~~any one of claims~~ claim 1 to 3, wherein the topography of the surface of the substrate is unchanged after the patterned stamp has been brought into contact with the substrate.

5. (Currently Amended) A method according to ~~any one of claims~~ claim 1 to 4, wherein the step of, comprising depositing the device layer is by spin coating or inkjet printing.

6. (Currently Amended) A method according to ~~any one of the preceding claims~~, claim 1, wherein the solvent is selected from the group consisting of xylene, ortho-xylene, toluene, benzene, mesitylene, chloroform, dichloromethane ~~or~~, and mixtures thereof.

7. (Canceled)

8. (Currently Amended) A method according to ~~any one of the preceding claims~~ claim 1, wherein in step (b) the surface energy in step (b) of any portion of the surface of the substrate that is in contact with the pattern stamp is modified.

9. (Original) A method according to claim 8, wherein the substrate comprises a polymer.

10. (Original) A method according to claim 9, wherein the polymer is poly(3,4-ethylenedioxythiophene) or polyaniline.

11. (Currently Amended) A method according to ~~any one of claims~~ claim 8 to 10, wherein the substrate is charged.

12. (Canceled)

13. A method according to any one of claims 1 to 7, wherein the patterned stamp is used as a mask in step (b) and step (b) includes subjecting any portion of the surface of the substrate that is not in contact with the patterned stamp to a surface energy modifying process.

14. (Original) A method according to claim 13, wherein the surface energy modifying process includes a step of exposing any portion of the surface of the substrate that is not in contact with the patterned stamp to UV radiation.

15. - 23. (Canceled